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With the principle of "Quality Parts, Customers Priority, Honest Operation, and Considerate Service", our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip, ALPS, ROHM, Xilinx, Pulse, ON, Everlight and Freescale. Main products comprise IC, Modules, Potentiometer, IC Socket, Relay, Connector. Our parts cover such applications as commercial, industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



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2SA1738

Silicon PNP epitaxial planar type

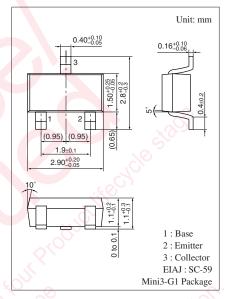
For high speed switching

■ Features

- High speed switching (Pair with 2SC3757)
- ullet Low collector-emitter saturation voltage $V_{CE(sat)}$
- Mini type package, allowing downsizing of the equipment and automatic insertion through the tape packing and the magazine packing.

■ Absolute Maximum Ratings $T_a = 25^{\circ}C$

Parameter	Symbol	Rating	Unit	
Collector-base voltage (Emitter open)	V_{CBO}	-15	V	
Collector-emitter voltage (Base open)	V_{CEO}	-15	V	
Emitter-base voltage (Collector open)	V_{EBO}	-4	V	
Collector current	I_{C}	-50	mA	
Peak collector current	I_{CP}	-100	mA	
Collector power dissipation	P _C	200	mW	
Junction temperature	T _j	150	°C	
Storage temperature	T _{stg}	-55 to +150	°C	



Marking Symbol: AK

■ Electrical Characteristics $T_a = 25$ °C ± 3 °C

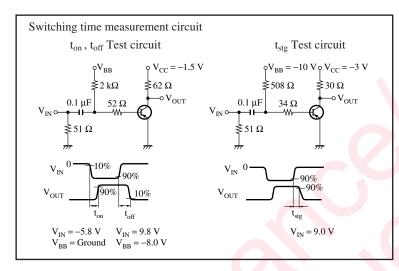
Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Collector-base cutoff current (Emitter open)	I_{CBO}	$V_{CB} = -8 \text{ V}, I_{E} = 0$	10	250	- 0.1	μΑ
Emitter-base cutoff current (Collector open)	I_{EBO}	$V_{EB} = -3 \text{ V}, I_C = 0$			- 0.1	μΑ
Forward current transfer ratio	h _{FE1} *	$V_{CE} = -1 \text{ V}, I_{C} = -10 \text{ mA}$	50		150	_
	h _{FE2}	$V_{CE} = -1 \text{ V}, I_{C} = -1 \text{ mA}$	30			
Collector-emitter saturation voltage	V _{CE(sat)}	$I_C = -10 \text{ mA}, I_B = -1 \text{ mA}$		- 0.1	- 0.2	V
Transition frequency	f_T	$V_{CB} = -10 \text{ V}, I_E = 10 \text{ mA}, f = 200 \text{ MHz}$	800	1500		MHz
Collector output capacitance	C _{ob}	$V_{CB} = -5 \text{ V}, I_E = 0, f = 1 \text{ MHz}$		1		pF
(Common base, input open circuited)		is white				
Turn-on time	t _{on}	Refer to the switching time measurement circuit		12		ns
Turn-off time	t _{off}	See Hill		20		ns
Storage time	t _{stg}			19		ns

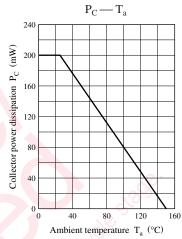
Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7030 measuring methods for transistors.

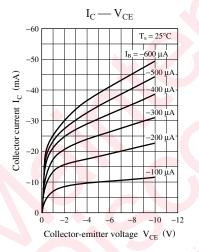
2. *: Rank classification

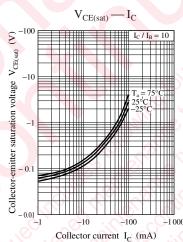
Rank	Q	R
h _{FE1}	50 to 120	90 to 150

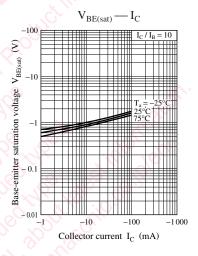
Panasonic

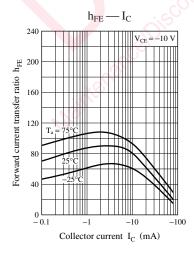


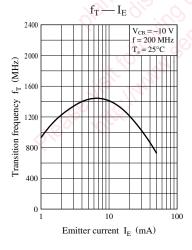


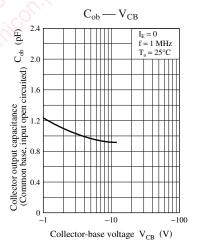












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